

Docket No. JCLA8534-D

Serial No. 10/728,150

REMARKS**1. Present Status of the Application**

Upon this response, claims 1, 6-9, 13-17, 25-29, 176, 177, 180, 186-189, 193-196, 200 and 202-230 remain pending in the present application. More specifically, claims 1, 6-9, 13-17, 25-29, 176, 177, 180, 186-189, 193-196, 200 and 202-203 are directly amended; claims 204-230 are newly added. It is believed that the foregoing amendments add no new matter to the present application.

2. Response To Objections/Rejections

Applicants respectfully traverse the rejections for at least the reasons set forth below.

Response To Claim 1

As amended, independent claim 1 is recited below:

1. A chip package structure comprising:
at least an integrated circuit die;
a metal layer deposited over said integrated circuit die and extending to a place under which there is no integrated circuit die; and
at least a passive device electrically connected to said integrated circuit die.

(emphasis added)

Applicants respectfully assert that the chip package claimed in claim 1 patentably distinguishes over the citations by Saito, by Eichelberger, and by Marcinkiewicz.

Docket No. JCLA8534-D**Serial No. 10/728,150**

Applicants teach that at least a passive device can be electrically connected to an integrated circuit die. The passive device may be a resistor, a capacitor, an inductor, a waveguide, a filter or a micro electronic mechanical sensor (MEMS), for example. However, Saito, Eichelberger and Marcinkiewicz fail to teach a passive device can be electrically connected to an integrated circuit die. Therefore, applicants consider that the above feature can not be anticipated in view of Saito's, Eichelberger's and Marcinkiewicz's device.

For at least the foregoing reasons, applicants respectfully submit independent claim 1 patentably defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 6-9, 13-17, 25-29 and 204-208 patentably define over the prior art as well.

Response To Claim 176

As amended, independent claim 176 is recited below:

176. A chip package structure comprising:
at least an integrated circuit die;
a metal layer deposited over said integrated circuit die and extending to a place under which there is no integrated circuit die; and
at least a passive device deposited at a place under which there is no integrated circuit die.

(emphasis added)

Applicants respectfully assert that the chip package claimed in claim 176 patentably distinguishes over the citations by Saito, by Eichelberger, and by Marcinkiewicz.

Docket No. JCLA8534-D

Serial No. 10/728,150

Applicants disclose that a passive device can be deposited at a place under which there is no integrated circuit die, which is not taught, hinted or suggested by Saito, by Eichelberger or by Marcinkiewicz. Therefore, applicants consider that the above feature can not be anticipated in view of Saito's, Eichelberger's and Marcinkiewicz's device.

For at least the foregoing reasons, applicants respectfully submit independent claim 176 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 177, 180, 186-189, 193-196, 200, 202-203 and 209-212 patently define over the prior art as well.

Response To Claim 213

As newly added, independent claim 213 is recited below:

213. A chip package structure comprising:
at least an integrated circuit die;
a metal layer deposited over said integrated circuit die and extending to a place under which there is no integrated circuit die; and
at least a passive device deposited over said integrated circuit die.

(emphasis added)

Applicants respectfully assert that the chip package claimed in claim 213 patentably distinguishes over the citations by Saito, by Eichelberger, and by Marcinkiewicz.

Applicants disclose that a passive device can be deposited over an integrated circuit die, which is not taught, hinted or suggested by Saito, by Eichelberger or by Marcinkiewicz.

Docket No. JCLA8534-D**Serial No. 10/728,150**

Therefore, applicants consider that the above feature can not be anticipated in view of Saito's, Eichelberger's and Marcinkiewicz's device.

For at least the foregoing reasons, applicants respectfully submit independent claim 213 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 214-230 patently define over the prior art as well.

Docket No. JCLA8534-D

Serial No. 10/728,150

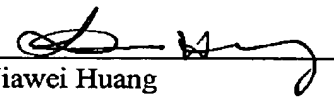
CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 1, 6-9, 13-17, 25-29, 176, 177, 180, 186-189, 193-196, 200 and 202-230 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Date: 2/15/2005

4 Venture, Suite 250
Irvine, CA 92618
Tel.: (949) 660-0761
Fax: (949)-660-0809

Respectfully submitted,
J.C. PATENTS


Jiawei Huang
Registration No. 43,330